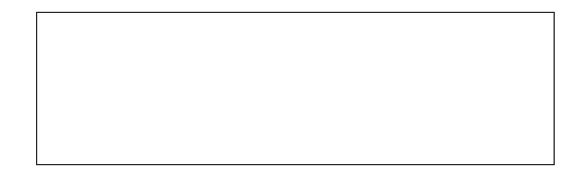


## COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PMP20654	REU: A	SUN REU	: Not In VersionControl		
	TID #: N/A					
PLOT NAME = Top Assembly Drawing	GENERATED : 12/15/	2016 5:35:02	PM	TEXAS INSTRUMENTS		



## COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP20654	REU: A	SUN REV	Not In VersionControl		
	TID #: N/A					
PLOT NAME = Bottom Assembly Drawing	GENERATED : 12/15/	2016 5: 35: 03	PM	TEXAS INSTRUMENTS		

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